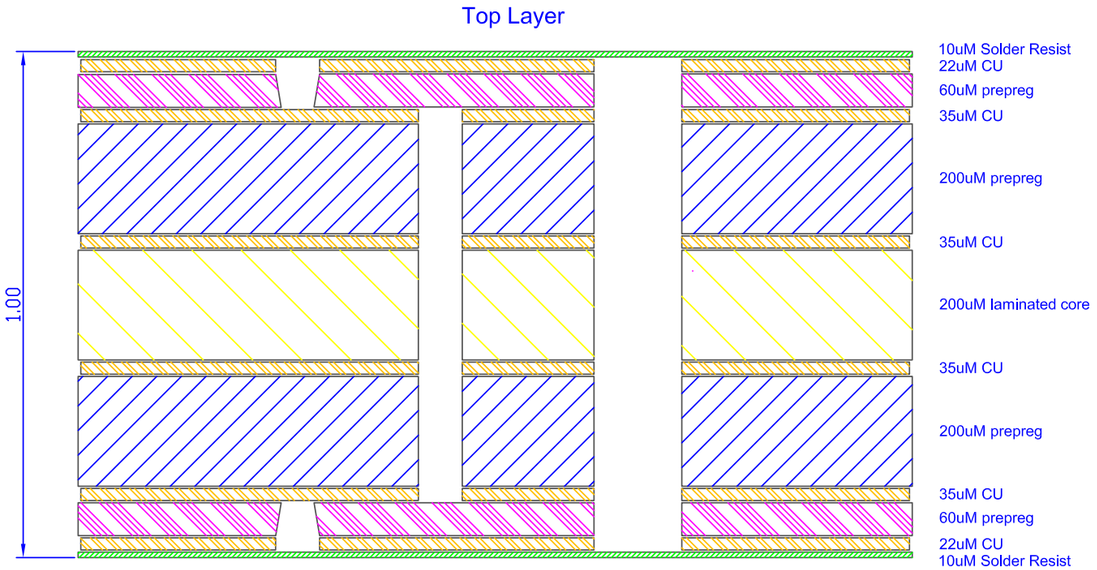

Surface Finishing : Chemical Gold Plate Ni 5 uM / Au 0.1 uM

Design Clearance

	Trace to Trace	Trace to Pad	Trace to Via	Via to Via	Via to Pad	Pad to Pad	Plane to Trace	Plane to Pad	Plane to Via	Plane to Plane
Layer 1	100um	100um	100um	100um	100um	200um	125um	150um	125um	150um
Layer 2	100um	100um	100um	100um	100um	200um	125um	150um	125um	150um
Layer 3	100um	100um	100um	100um	100um	200um	125um	150um	125um	150um
Layer 4	100um	100um	100um	100um	100um	200um	125um	150um	125um	150um
Layer 5	**75um(*)**	**75um(*)**	**75um(*)**	100um	100um	200um	125um	150um	125um	150um
Layer 6	**75um(*)**	**75um(*)**	**75um(*)**	100um	100um	200um	125um	150um	125um	150um

(*) 75um apply under 0.5mm pitch BGA, otherwise 100um

Design Rules

	Trace Width	Laser Via Pad	Buried Via Pad	
Layer 1	100um	250um		
Layer 2	75um	275um	550um	
Layer 3	100um		550um	
Layer 4	75um		550um	
Layer 5	75um	250um	550um	
Layer 6	75um	275um		

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Engineer Vlacci M.	NEONSEVEN s.r.l.
Drawn by Arban P.	
R&D CHK	TITLE: DESIGN RULES (DRU) Size A3
DOC CTRL CHK	
MFG ENGR CHK	
QA CHK	

Changed by Vlacci M.	Date Changed Tuesday, July 19, 2005	Time Changed 12:07:05 pm		Drawing Number BH02_HW_HD_029000	Sheet 1 of 1